



STGD5NB120SZ-1

N-CHANNEL 5A - 1200V IPAK INTERNALLY CLAMPED PowerMESH™ IGBT

TYPE	V _{CES}	V _{CE(sat)}	I _C
STGD5NB120SZ-1	1200 V	< 2.0 V	5 A

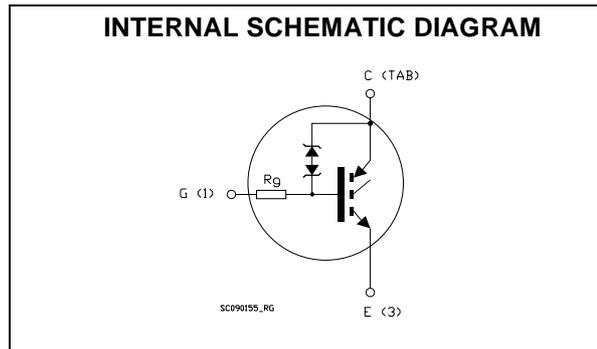
- HIGH INPUT IMPEDANCE (VOLTAGE DRIVEN)
- LOW ON-VOLTAGE DROP (V_{cesat})
- HIGHT CURRENT CAPABILITY
- OFF LOSSES INCLUDE TAIL CURRENT
- HIGH VOLTAGE CLAMPING FEATURES

DESCRIPTION

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH™ IGBTs, with outstanding performances. The suffix "S" identifies a family optimized achieve minimum on-voltage drop for low frequency applications (<1kHz). The built in collector-gate zener exhibits a very precise active clamping.

APPLICATIONS

- LIGHT DIMMER
- INRUSH CURRENT LIMITATION



ORDERING INFORMATION

SALES TYPE	MARKING	PACKAGE	PACKAGING
STGD5NB120SZ-1	GD5NB120SZ	IPAK	TUBE

STGD5NB120SZ-1

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CES}	Collector-Emitter Voltage ($V_{GS} = 0$)	1200	V
V_{ECR}	Emitter-Collector Voltage	20	V
V_{GE}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current (continuous) at $T_C = 25^\circ\text{C}$	10	A
I_C	Collector Current (continuous) at $T_C = 100^\circ\text{C}$	5	A
$I_{CM} (\blacksquare)$	Collector Current (pulsed)	20	A
P_{TOT}	Total Dissipation at $T_C = 25^\circ\text{C}$	55	W
	Derating Factor	0.4	W/ $^\circ\text{C}$
$E_{as} (1)$	Single Pulse Avalanche Energy at $T_j = 25^\circ\text{C}$ Single Pulse Avalanche Energy at $T_j = 100^\circ\text{C}$	10 7	mJ mJ
T_{stg}	Storage Temperature	-65 to 150	$^\circ\text{C}$
T_j	Operating Junction Temperature range	150	$^\circ\text{C}$

(\blacksquare) Pulse width limited by safe operating area

(1) $V_{CE} = 50\text{ V}$, $I_{AV} = 3.3\text{ A}$

THERMAL DATA

Rthj-case	Thermal Resistance Junction-case Max	2.27	$^\circ\text{C}/\text{W}$
Rthj-amb	Thermal Resistance Junction-ambient Max	100	$^\circ\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS ($T_{CASE} = 25^\circ\text{C}$ UNLESS OTHERWISE SPECIFIED)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{BR(CES)}$	Collector-Emitter Breakdown Voltage	$I_C = 10\text{ mA}$, $V_{GE} = 0\text{ V}$	1200			V
I_{CES}	Collector cut-off Current ($V_{GE} = 0$)	$V_{CE} = 900\text{ V}$ $V_{CE} = 900\text{ V}$, $T_j = 125^\circ\text{C}$			50 250	μA μA
I_{GES}	Gate-Emitter Leakage Current ($V_{CE} = 0$)	$V_{GE} = \pm 20\text{ V}$, $V_{CE} = 0\text{ V}$			± 100	nA

ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{GE(th)}$	Gate Threshold Voltage	$V_{CE} = V_{GE}$, $I_C = 250\text{ }\mu\text{A}$	2		5	V
V_{GE}	Gate Emitter Voltage	$V_{CE} = 2.5\text{ V}$, $I_C = 2\text{ A}$, $T_j = 25\div 125^\circ\text{C}$			6.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE} = 15\text{ V}$, $I_C = 5\text{ A}$ $V_{GE} = 15\text{ V}$, $I_C = 5\text{ A}$, $T_j = 125^\circ\text{C}$		1.3	2.0	V V

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g_{fs}	Forward Transconductance	$V_{CE} = 25\text{ V}$, $I_C = 5\text{ A}$		5		S
$C_{ies}^{(*)}$	Input Capacitance	$V_{CE} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{GE} = 0\text{ V}$		430		pF
$C_{oes}^{(*)}$	Output Capacitance			40		pF
$C_{res}^{(*)}$	Reverse Transfer Capacitance			7		pF
R_g	Gate Resistance			4		K Ω

Note: (*) Without R_g Gate Resistance

FUNCTIONAL TEST

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{as}	Unclamped inductive switching current	$V_{CC} = 50\text{ V}$, $L = 1.8\text{ mH}$ $T_{start} = 25^\circ\text{C}$, $R_{drive} = 1\text{ K}\Omega$	3.3			A
I_{CL}	Latching Current	$V_{CLAMP} = 960\text{ V}$, $T_j = 125^\circ\text{C}$ $R_{drive} = 1\text{ K}\Omega$		10		A

ELECTRICAL CHARACTERISTICS

SWITCHING ON

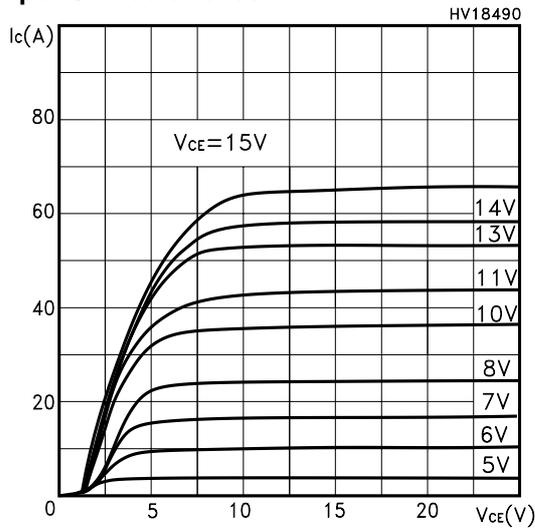
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Delay Time Rise Time	$I_C = 5\text{ A}$, $V_{CC} = 960\text{ V}$ $V_{GE} = 15\text{ V}$, $R_{drive} = 1\text{ K}\Omega$ $T_j = 25^\circ\text{C}$		690 160		ns ns
$(di/dt)_{on}$ E_{on}	Turn-on Current Slope Turn-on Switching Losses		$I_{CC} = 5\text{ A}$, $V_{CC} = 960\text{ V}$ $V_{GE} = 15\text{ V}$, $R_{drive} = 1\text{ K}\Omega$ $T_j = 125^\circ\text{C}$		39 2.64	

SWITCHING OFF

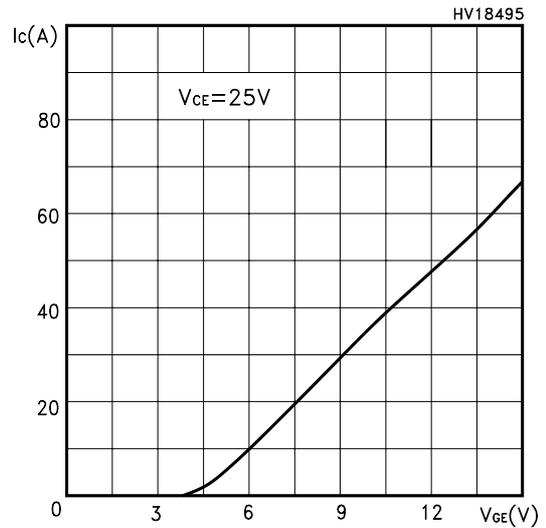
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
t_c $t_r(V_{off})$ $t_{d(off)}$ t_f $E_{off}^{(**)}$	Cross-over Time Off Voltage Rise Time Delay Time Fall Time Turn-off Switching Loss	$I_C = 5\text{ A}$, $V_{CC} = 960\text{ V}$ $V_{GE} = 15\text{ V}$, $R_{drive} = 1\text{ K}\Omega$ $T_j = 25^\circ\text{C}$		4 2.2 12.1 1.13 9		μs μs μs μs mJ
t_c $t_r(V_{off})$ $t_{d(off)}$ t_f $E_{off}^{(**)}$	Cross-over Time Off Voltage Rise Time Delay Time Fall Time Turn-off Switching Loss		$I_C = 5\text{ A}$, $V_{CC} = 960\text{ V}$ $V_{GE} = 15\text{ V}$, $R_{drive} = 1\text{ K}\Omega$ $T_j = 125^\circ\text{C}$		5 2.2 12.1 2 10.2	

(**) Losses include Also the Tail (Jedec Standardization)

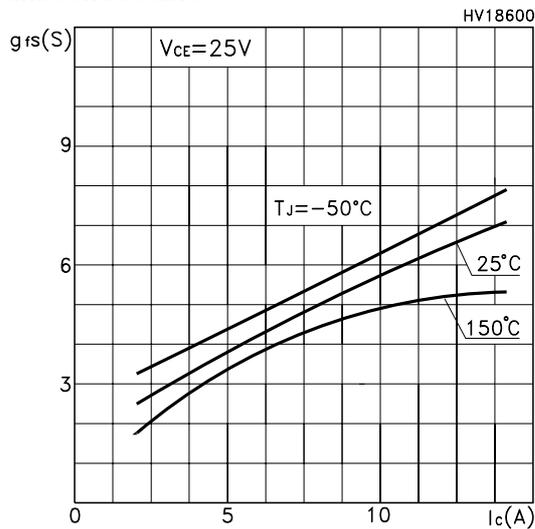
Output Characteristics



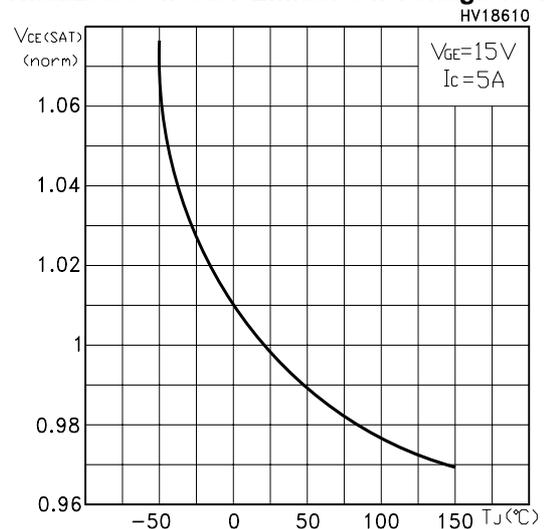
Transfer Characteristics



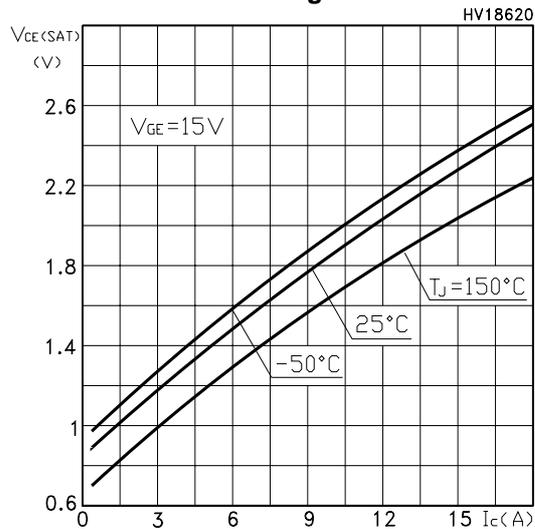
Transconductance



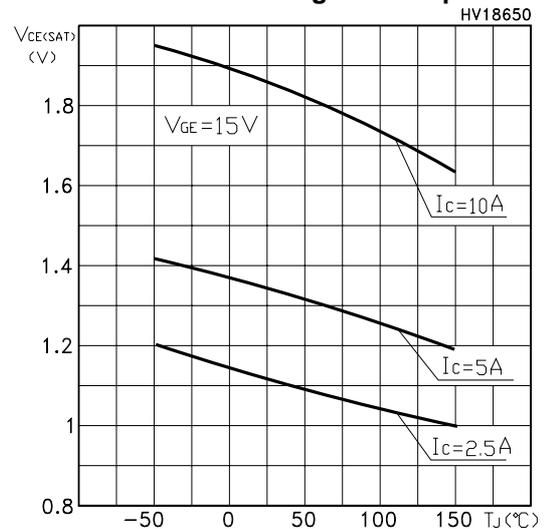
Normalized Collector-Emitter On Voltage vs Temp.



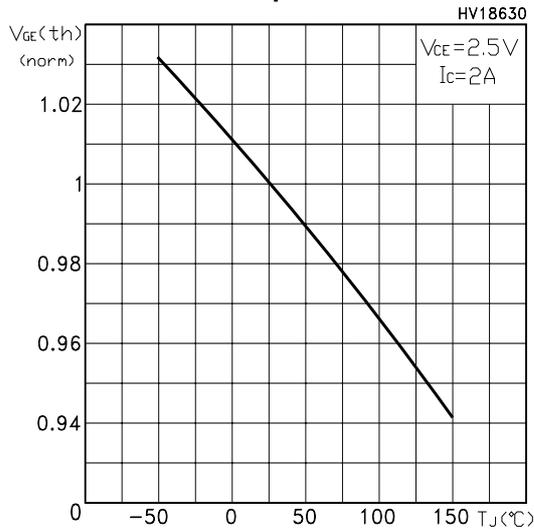
Collector-Emitter On Voltage vs Collector Current



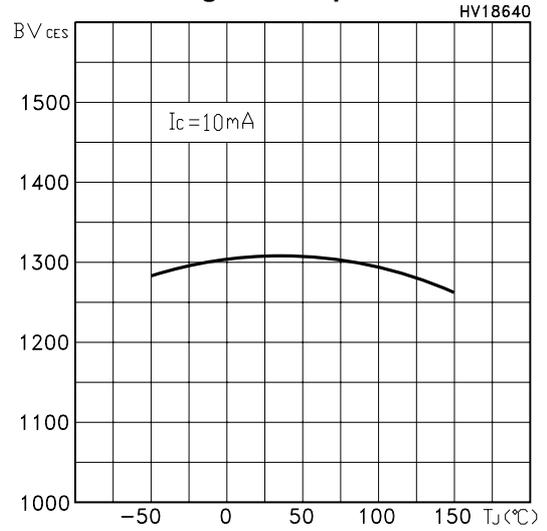
Collector-Emitter On Voltage vs Temperature



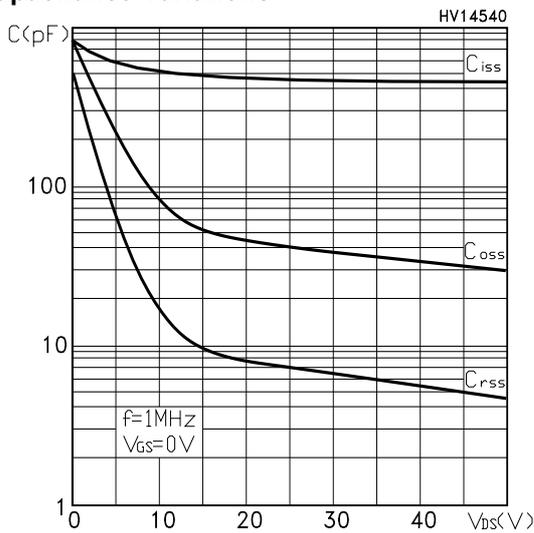
Gate Threshold vs Temperature



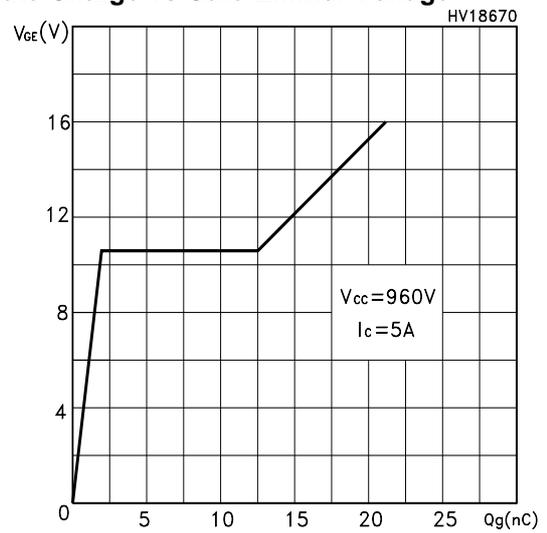
Breakdown Voltage vs Temperature



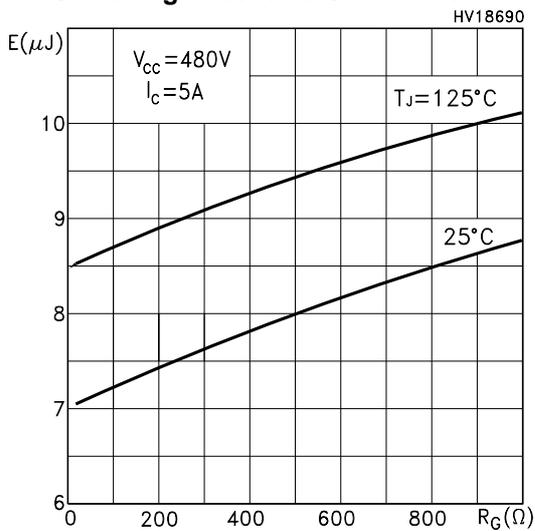
Capacitance Variations



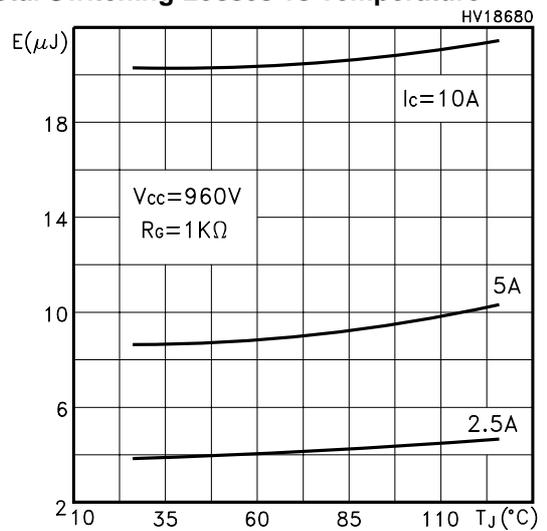
Gate Charge vs Gate-Emitter Voltage



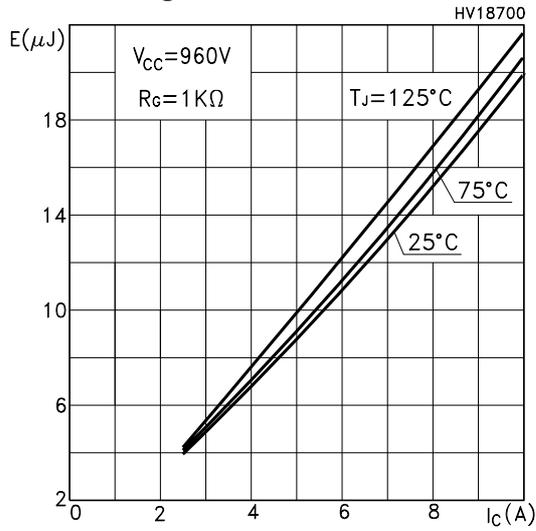
Total Switching Losses vs Gate Resistance



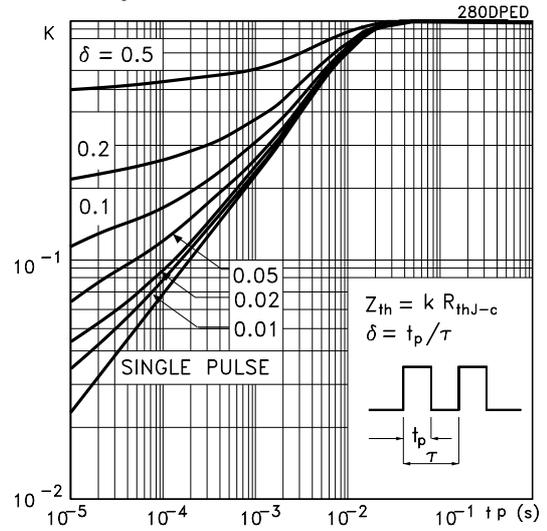
Total Switching Losses vs Temperature



Total Switching Losses vs Collector Current



Thermal Impedance



Turn-Off SOA

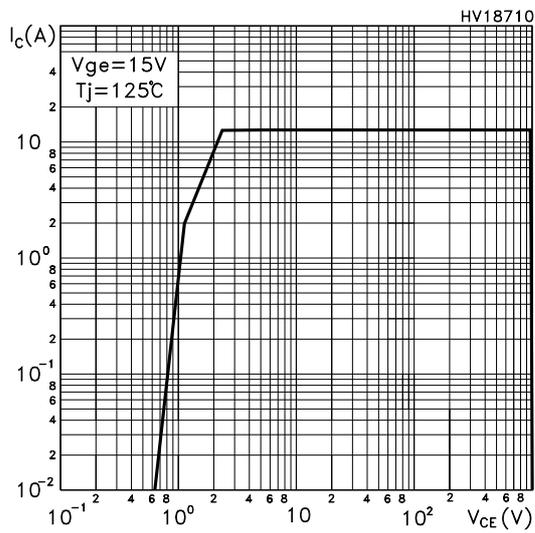


Fig. 1: Gate Charge test Circuit

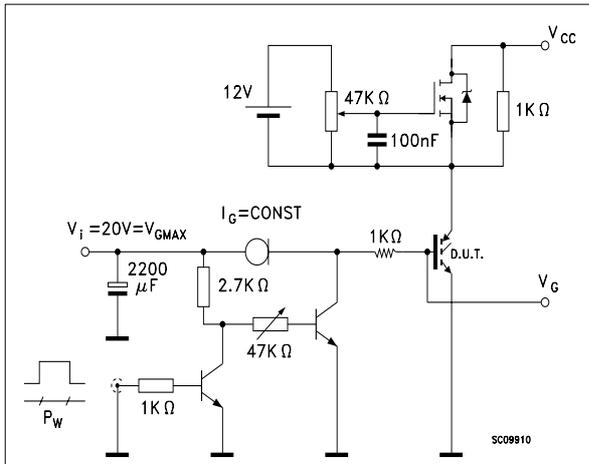
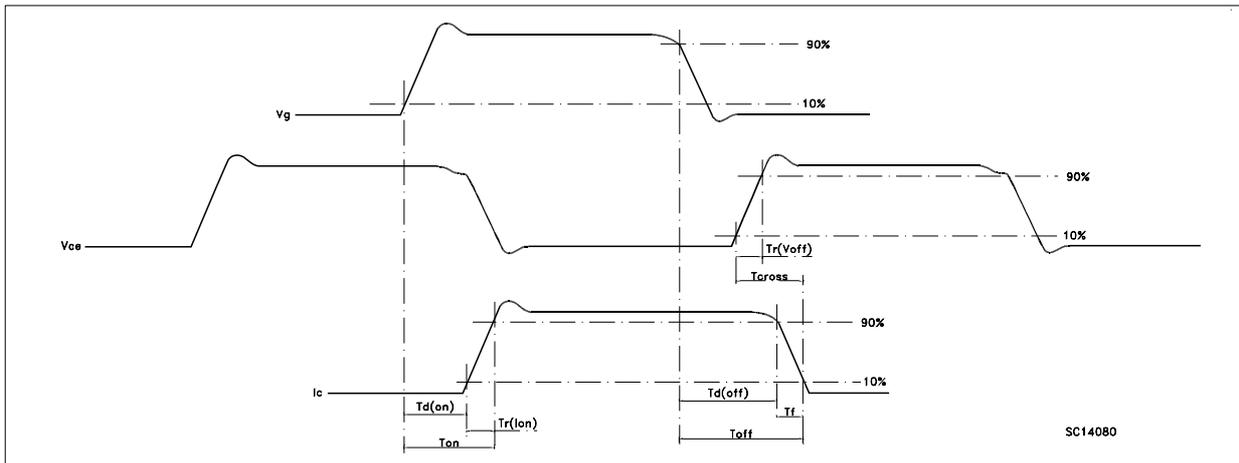
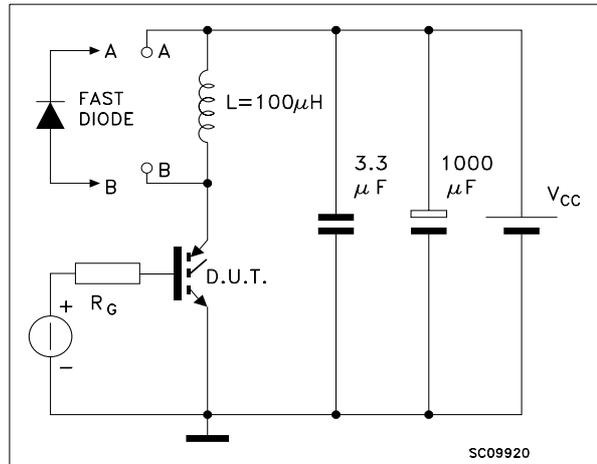
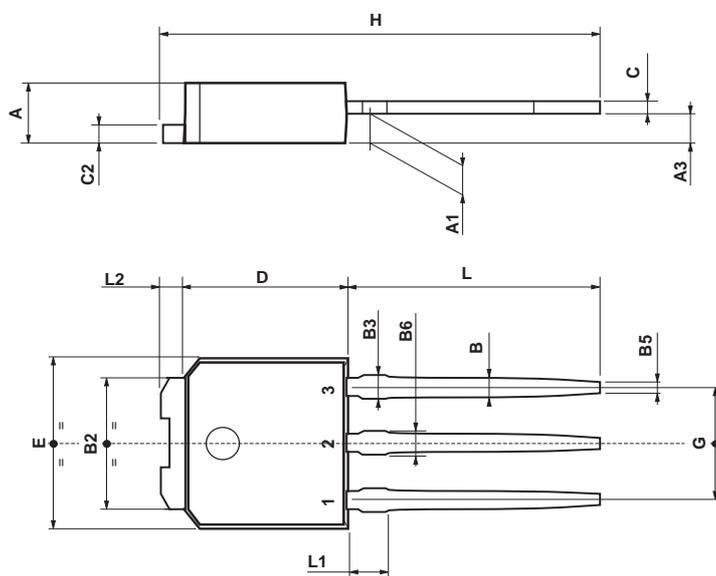


Fig. 2: Test Circuit For Inductive Load Switching (SC09920)



TO-251 (IPAK) MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A3	0.7		1.3	0.027		0.051
B	0.64		0.9	0.025		0.031
B2	5.2		5.4	0.204		0.212
B3			0.85			0.033
B5		0.3			0.012	
B6			0.95			0.037
C	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
E	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
H	15.9		16.3	0.626		0.641
L	9		9.4	0.354		0.370
L1	0.8		1.2	0.031		0.047
L2		0.8	1		0.031	0.039



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